PRODUCT SPECIFICATION

0.9” TFT LCD MODULE
MODEL: YDP LCD I R 90 S

ROHS

< ◇> Preliminary Specification

< ◆> Finally Specification

CUSTOMER’S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED BY	PM REVIEWED	PD REVIEWED	PREPARED BY
-	TFT S. G. H 20240828	TFT 周福云 20240828	TFT L. L 20240828

knitter-switch

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2024.08.28	LL	Initial Release	

Table of Contents

1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	0.9”	
LCD type	IPS TFT	
Display Mode	Transmissive /Normally Black	
Resolution	128 RGB x 128	Pixels
View Direction	Full viewing	Best Image
Module Outline	TBD	mm
Active Area	23.04(H) x 23.04(V)	mm
Pixel Pitch	180(H) x 180(V)	um
Pixel Arrangement	RGB Vertical stripe	
Display Colors	16.7M	
Interface	4-SPI	
Driver IC	ST7735P3	
With or without the touch panel	Without	
Operating Temperature	**-20～70**	ºC
Storage Temperature	**-30～80**	ºC
Weight	TBD	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

GND=0V, Ta=25ºC

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.3	4.6	V
Storage temperature	T_{STG}	**-30**	**+80**	ºC
Operating temperature	T_{OP}	**-20**	**+70**	ºC

Note 1: If Ta below 50ºC, the maximal humidity is 90%RH, if Ta over 50ºC, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10℃, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	VDD	2.5	2.8	3.3	V
Logic Low input voltage	V_{IL}	GND	-	0.3*VDD	V
Logic High input voltage	V_{IH}	0.7*VDD	-	VDD	V
Logic Low output voltage	V_{OL}	GND	-	0.2*VDD	V
Logic High output voltage	V_{OH}	0.8*VDD	-	VDD	V
Current Consumption All White	I_{DD}	-	TBD	-	mA

5. Backlight Characteristic

TBD

6. Optical Characteristics

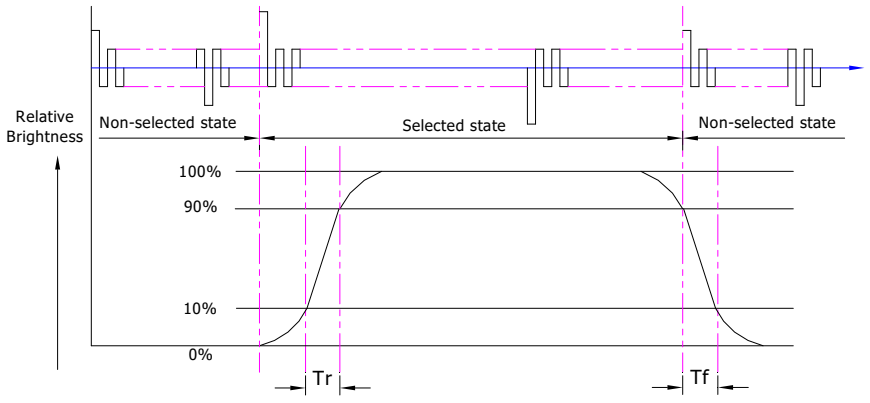
6.1. Optical Characteristics

Ta=25ºC, VDD=2.8V

	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
Backlight On (Transmissive Mode)	Luminance on TFT(I_f =20mA/LED)		Lv	Normally viewing angle θX = φY =0º	-	**TBD**	-	cd/m²
	Contrast ratio(See 6.3)		CR		800	1200	-	
	Response time (See 6.2)		TR+TF		-	25	35	ms
	Chromaticity Transmissive (See6.5)	Red	XR		-	**TBD**	-	
			YR		-	**TBD**	-	
		Green	XG		-	**TBD**	-	
			YG		-	**TBD**	-	
		Blue	XB		-	**TBD**	-	
			YB		-	**TBD**	-	
		White	XW		-	**TBD**	-	
			YW		-	**TBD**	-	
	Viewing Angle (See 6.4)	Horizontal	θX+	Center CR≥10	80	85	-	Deg.
			θX-		80	85	-	
		Vertical	φY+		80	85	-	
			φY-		80	85	-	
	NTSC Ratio(Gamut)				60	65	-	%

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

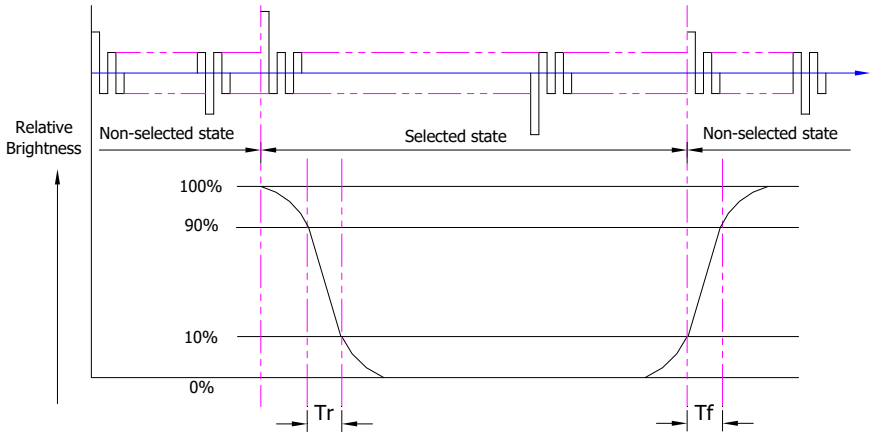


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

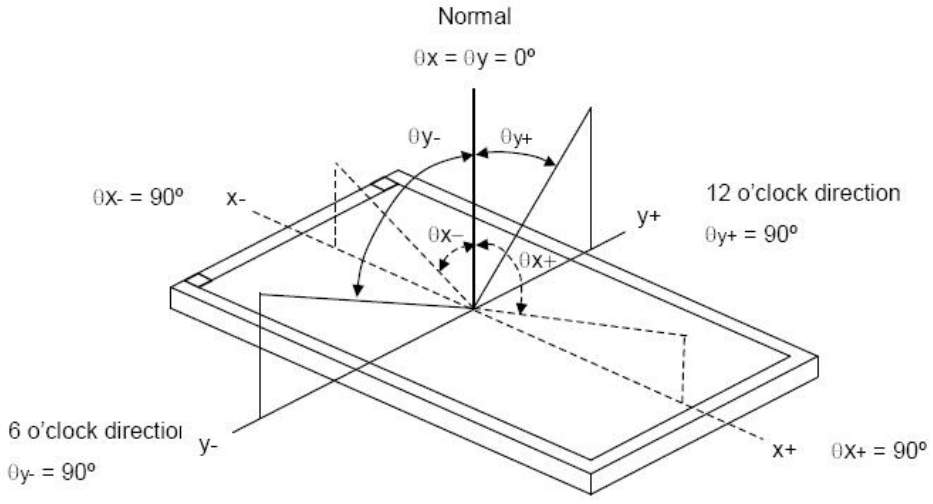
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



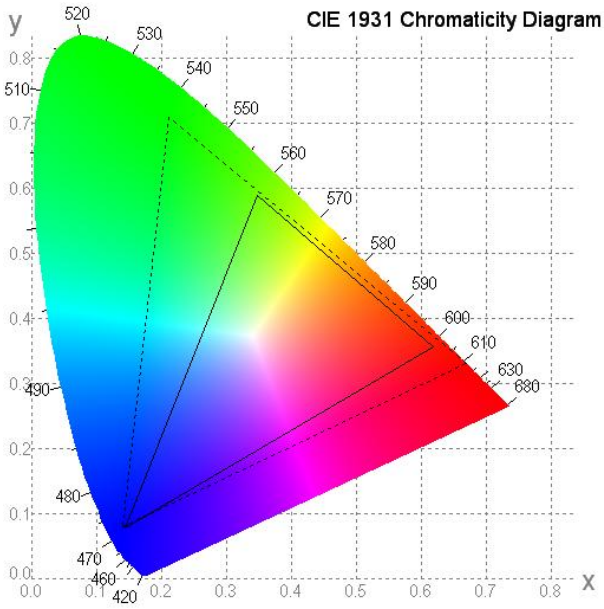
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

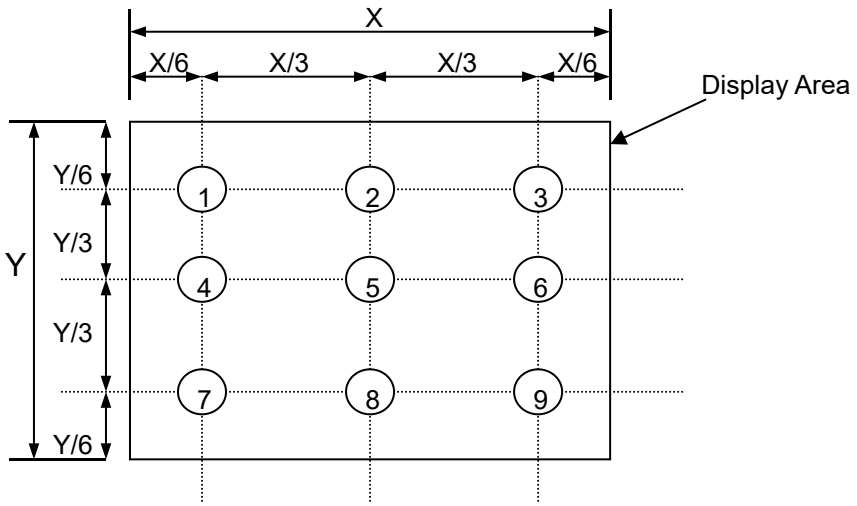
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: L_V = average (L_{P1}:L_{P9})

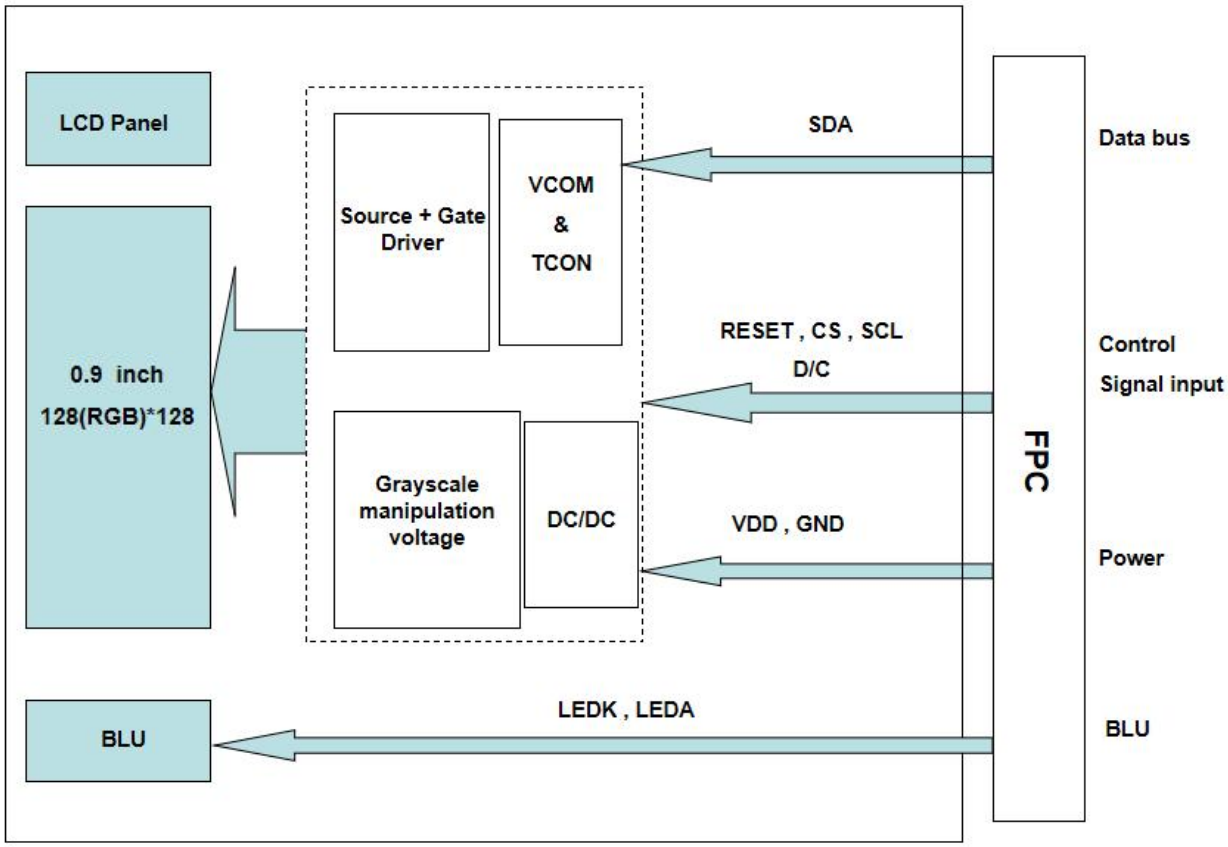
6.6.2. Uniformity = Minimal (L_{P1}:L_{P9}) / Maximal (L_{P1}:L_{P9}) * 100%

6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply



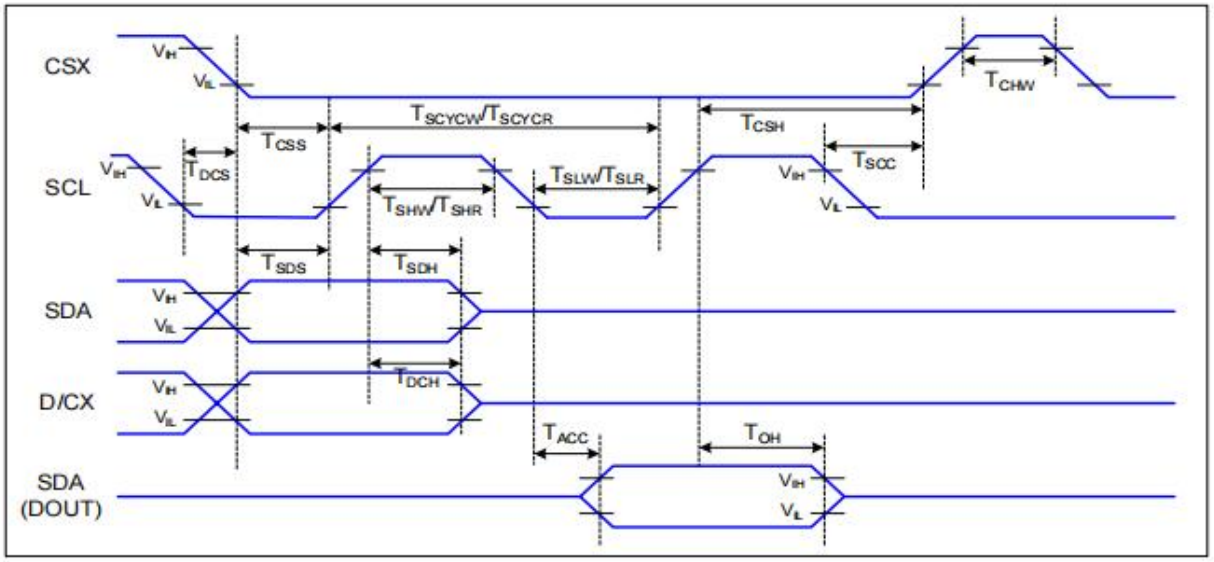
8. Interface Pins Definition

FPC:

No.	Symbol	Function	Remark
1	GND	Ground	
2	LEDK	LED Cathode	
3	LEDA	LED Anode	
4	VDD	Power supply	
5	GND	Ground	
6	GND	Ground	
7	D/C	Data or command	
8	CS	Chip select pin.	
9	SCL	This pin is used to be serial interface clock	
10	SDA	SPI interface input/output pin.the data is latched on the rising edge of the SCL signal	
11	RESET	This signal will reset the device and it must be applied to properly initialize the chip.Signal is active low	
12	GND	Ground	

9. AC Characteristics

9.1. Display Serial Interface Timing Characteristics (4-line SPI system)



Ta=25 ℃, VDDI=1.65~3.7V, VDD=2.5~3.7V

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	TCSS	Chip Select Setup Time (Write)	45		ns	
	TCSH	Chip Select Hold Time (Write)	45		ns	
	TCSS	Chip Select Setup Time (Read)	60		ns	
	TSCC	Chip Select Hold Time (Read)	65		ns	
	TCHW	Chip Select "H" Pulse Width	40		ns	
SCL	TSCYCW	Serial Clock Cycle (Write)	20		ns	-Write Command & Data Ram
	TSHW	SCL "H" Pulse Width (Write)	10		ns	
	TSLW	SCL "L" Pulse Width (Write)	10		ns	
	TSCYCR	Serial Clock Cycle (Read)	150		ns	-Read Command & Data Ram
	TSHR	SCL "H" Pulse Width (Read)	60		ns	
	TSLR	SCL "L" Pulse Width (Read)	60		ns	
D/CX	TDCS	D/CX Setup Time	10		ns	
	TDCH	D/CX Hold Time	10		ns	
SDA (DIN) (DOUT)	TSDS	Data Setup Time	10		ns	For Maximum CL=30pF For Minimum CL=8pF
	TSDH	Data Hold Time	10		ns	
	TACC	Access Time	10	50	ns	
	TOH	Output Disable Time	15	50	ns	

Table 7 4-line Serial Interface Characteristics

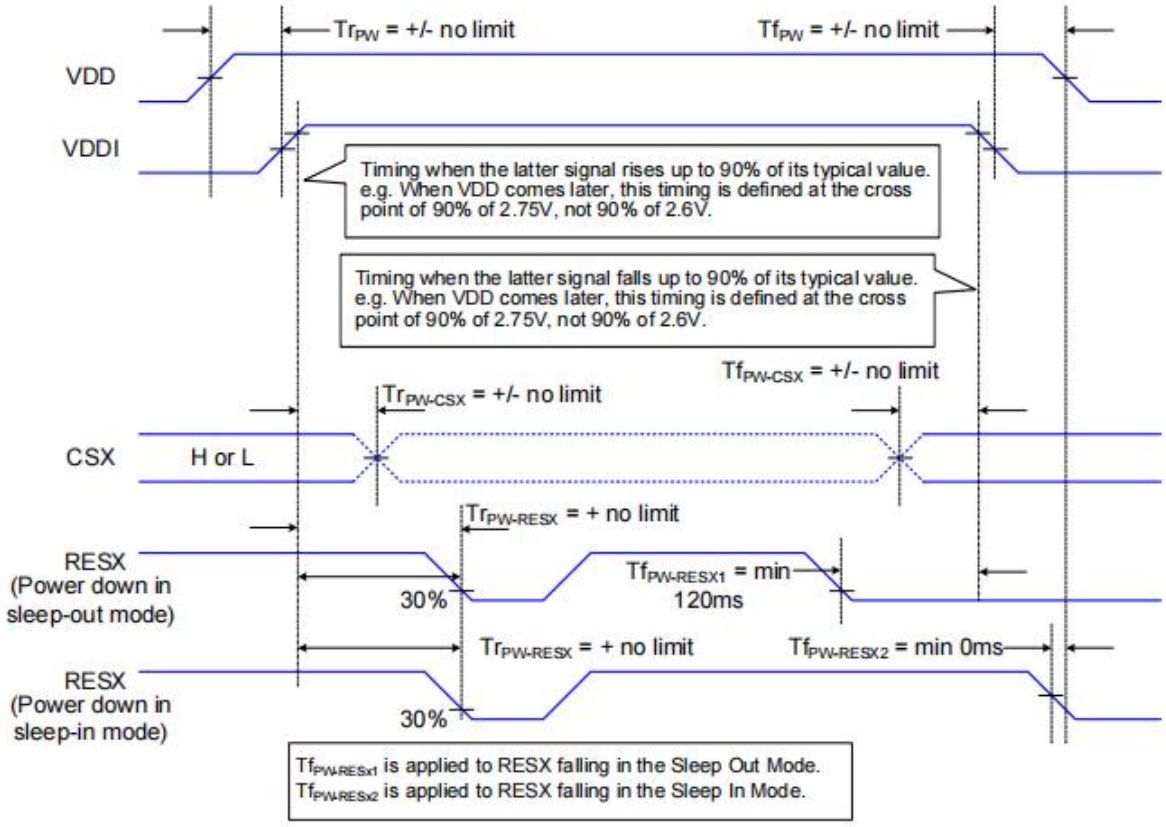
Note : The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

9.2. Power ON/OFF Sequence

VDDI and VDD can be applied in any order
VDD and VDDI can be powered down in any order
During power off, if LCD is in the Sleep Out mode, VDD and VDDI must be powered down minimum 120msec after RESX has been released.
During power off, if LCD is in the Sleep In mode, VDDI or VDD can be powered down minimum 0msec after RESX has been released.
CSX can be applied at any timing or can be permanently grounded. RESX has priority over CSX.

Note 1: There will be no damage to the display module if the power sequences are not met.
Note 2: There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.
Note 3: There will be no abnormal visible effects on the display between end of Power On Sequence and before receiving Sleep Out
command. Also between receiving Sleep In command and Power Off Sequence.
Note 4: If RESX line is not held stable by host during Power On Sequence as defined in the sequence below, then it will be necessary to
apply a Hardware Reset (RESX) after Host Power On Sequence is complete to ensure correct operation. Otherwise function is
not guaranteed.

The power on/off sequence is illustrated below



1) Uncontrolled Power Off

The uncontrolled power-off means a situation which removed a battery without the controlled power off sequence. It will neither damage the module or the host interface.

If uncontrolled power-off happened, the display will go blank and there will not any visible effect on the display(blank display) and remains blank until “Power On Sequence” powers it up.

10. Quality Assurance

10.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3. Nonconforming Analysis & Disposition

10.3.1. Nonconforming analysis:

10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

10.3.1.3. If can not finish the analysis on time, customer will be notified with the progress status.

10.3.2. Disposition of nonconforming:

10.3.2.1. Non-conforming product over PPM level will be replaced.

10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

10.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

10.4.1. There is any discrepancy in standard of quality assurance.

10.4.2. Additional requirement to be added in product specification.

10.4.3. Any other special problem.

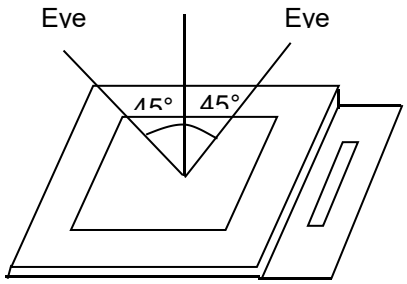
10.5. Standard of the Product Visual Inspection

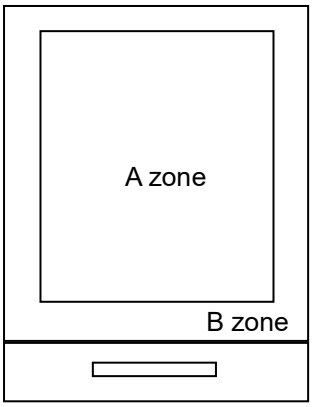
10.5.1. Appearance inspection:

10.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm ± 2cm.

10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



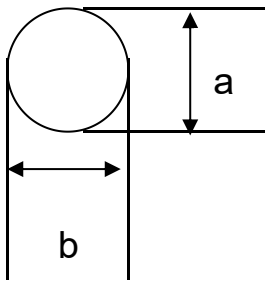


10.5.2. Basic principle:

10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

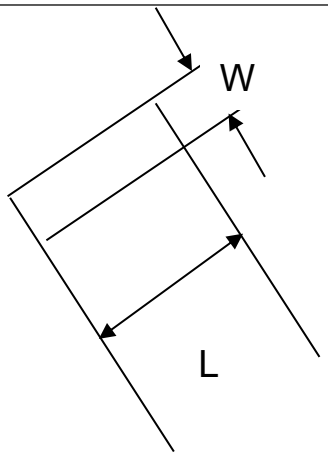
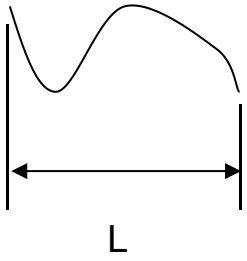
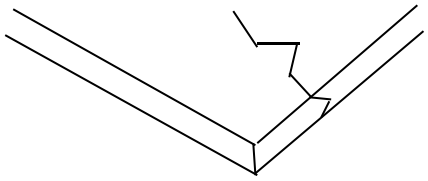
10.5.2.2. New item must be added on time when it is necessary.

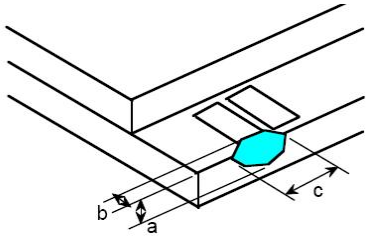
10.6. Inspection Specification

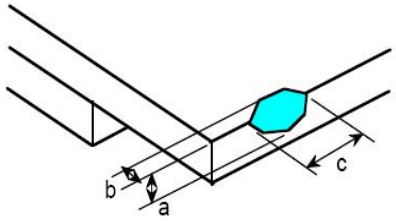
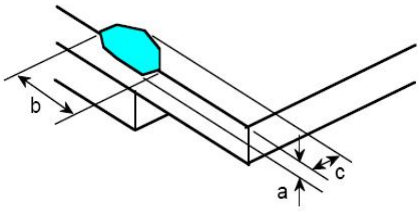
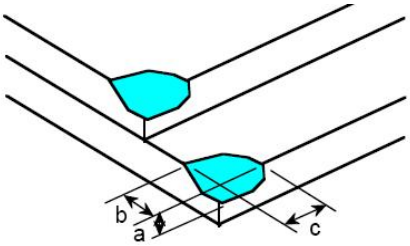
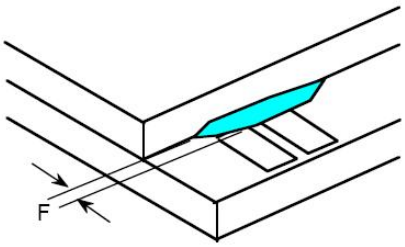
<table>
<tr><th>No.</th><th>Item</th><th>Criteria (Unit: mm)</th></tr>
<tr><td>01</td><td>Black / White spot
Foreign material
(Round type)
Pinholes
Stain
Particles inside cell.
(Minor defect)</td><td>


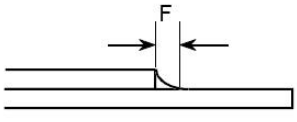
<table>
<tr><th>Area / Size</th><th>Acc. Qty</th></tr>
<tr><td>φ≤0.10</td><td>Ignore</td></tr>
<tr><td>0.10<φ≤0.15</td><td>2</td></tr>
<tr><td>0.15<φ≤0.25</td><td>1</td></tr>
<tr><td>0.25<φ</td><td>0</td></tr>
<tr><td>Total</td><td>2 no include φ≤ 0.10</td></tr>
</table>
φ= (a + b) /2

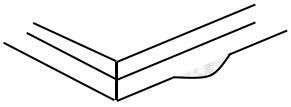
Distance between 2 defects should more than 3mm apart.
</td></tr>
<tr><td>02</td><td>Electrical Defect
(Minor defect)</td><td>
<table>
<tr><td></td><td>Display Area</td><td>Total</td><td rowspan="4">Note1</td></tr>
<tr><td>Bright dot</td><td>0</td><td>0</td></tr>
<tr><td>Dark dot</td><td>N⩽2</td><td>N⩽2</td></tr>
<tr><td>Total dot</td><td>N⩽2</td><td>N⩽2</td></tr>
<tr><td>Mura</td><td colspan="2">Not visible through 5% ND filters.</td><td>Note2</td></tr>
</table>
Remark:
1. Bright dot caused by scratch and foreign object accords to item 1.
</td></tr>
</table>

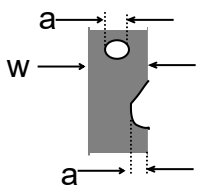
03	Black and White line Scratch Foreign material (Line type) (Minor defect)	  Length / Width / Acc. Qty / / W ≦ 0.03 / Ignore L ≦ 2.5 / 0.03 < W ≦ 0.05 / 3 L ≦ 2.5 / 0.05 < W ≦ 0.10 / 2 / / 0.1 < W / Total / 3 Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.
04	Glass Crack (Minor defect)	 Crack is potential to enlarge, any type is not allowed.

05	Glass Chipping Pad Area: (Minor defect) 	Length and Width / Acc. Qty c > 3.0, b< 1.0 / 1 c< 3.0, b< 1.0 / 3 a<Glass Thickness
06	Glass Chipping Rear of Pad Area: (Minor defect)	Length and Width / Acc. Qty c > 3.0, b< 1.0 / 1 c< 3.0, b< 1.0 / 2 c< 3.0, b< 0.5 / 4 a<Glass Thickness

<table>
<tr><td></td><td> 
</td><td></td></tr>
<tr><td>07</td><td>Glass Chipping Except Pad Area:
(Minor defect)
 
</td><td><table>
<tr><td>Length and Width</td><td>Acc. Qty</td></tr>
<tr><td>c > 3.0, b< 1.0</td><td>1</td></tr>
<tr><td>c< 3.0, b< 1.0</td><td>2</td></tr>
<tr><td>c< 3.0, b< 0.5</td><td>4</td></tr>
<tr><td colspan="2">a<Glass Thickness</td></tr>
</table></td></tr>
<tr><td>08</td><td>Glass Corner Chipping:
(Minor defect)
 
</td><td><table>
<tr><td>Length and Width</td><td>Acc. Qty</td></tr>
<tr><td>c < 3.0, b< 3.0</td><td>Ignore</td></tr>
<tr><td colspan="2">a<Glass Thickness</td></tr>
</table></td></tr>
<tr><td>09</td><td>Glass Burr:
(Minor defect)
 

  </td><td><table>
<tr><td>Length</td><td>Acc. Qty</td></tr>
<tr><td>F < 1.0</td><td>Ignore</td></tr>
</table>
Glass burr don’t affect assemble and module dimension.</td></tr>
</table>

<table>
<tr><td>10</td><td>FPC Defect:
(Minor defect)
  </td><td>10.1 Dent, pinhole width a<w/3.
(w: circuitry width.)
10.2 Open circuit is unacceptable.
10.3 No oxidation, contamination and distortion.</td></tr>
<tr><td>11</td><td>Bubble on Polarizer
(Minor defect)</td><td><table><tr><td>Diameter</td><td>Acc. Qty</td></tr><tr><td>φ≤0.20</td><td>Ignore</td></tr><tr><td>0.20 <φ≤0.30</td><td>4</td></tr><tr><td>0.30 <φ≤0.50</td><td>1</td></tr><tr><td>0.50 < φ</td><td>None</td></tr></table></td></tr>
<tr><td>12</td><td>Dent on Polarizer
(Minor defect)</td><td><table><tr><td>Diameter</td><td>Acc. Qty</td></tr><tr><td>φ≤0.20</td><td>Ignore</td></tr><tr><td>0.20 <φ≤0.30</td><td>4</td></tr><tr><td>0.30 <φ≤0.50</td><td>1</td></tr><tr><td>0.50 < φ</td><td>None</td></tr></table></td></tr>
<tr><td>13</td><td>Bezel</td><td>13.1 No rust, distortion on the Bezel.
13.2 No visible fingerprints, stains or other contamination.</td></tr>
<tr><td>14</td><td>PCB</td><td>14.1 No distortion or contamination on PCB terminals.
14.2 All components on PCB must same as documented on the BOM/component layout.
14.3 Follow IPC-A-600F.</td></tr>
<tr><td>15</td><td>Soldering</td><td>Follow IPC-A-610C standard</td></tr>
<tr><td>16</td><td>Electrical Defect
(Major defect)</td><td>The below defects must be rejected.
16.1 Missing vertical / horizontal segment,
16.2 Abnormal Display.
16.3 No function or no display.
16.4 Current exceeds product specifications.
16.5 LCD viewing angle defect.
16.6 No Backlight.
16.7 Dark Backlight.
16.8 Touch Panel no function.</td></tr>
</table>

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.

10.7.2. Two minor defects are equal to one major in lot sampling inspection.

10.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

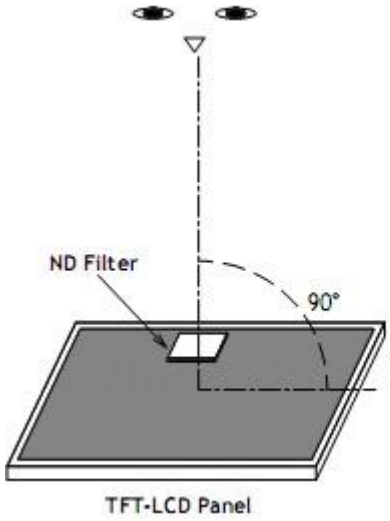
10.9. Packaging

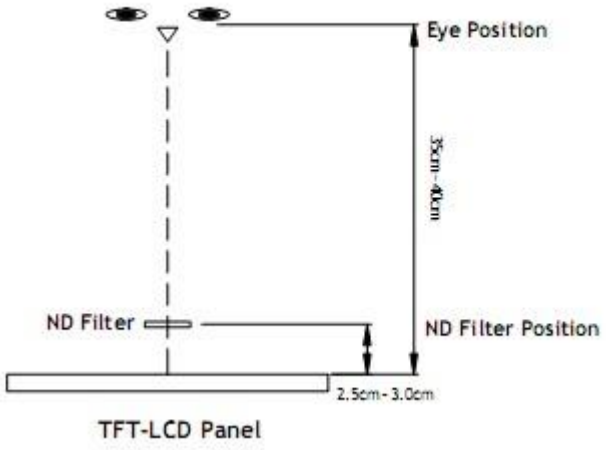
10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.

10.9.2. Modules inside package box should have compliant mark.

10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.





Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	**70℃, 96Hrs**	2	GB/T2423.2 -2008
2	Low Temperature Operating	**-20℃, 96Hrs**	2	GB/T2423.1 -2008
3	High Humidity Storage	**50℃, 90%RH, 96Hrs**	2	GB/T2423.3 -2016
4	High Temperature Storage	**80℃, 96Hrs**	2	GB/T2423.2 -2008
5	Low Temperature Storage	**-30℃, 96Hrs**	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	**-20℃, 60min~70℃, 60min, 20 cycles.**	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air:±4KV 150pF/330Ω 5 times	2	GB/T17626.2 -2018
		Contact:±2KV 150pF/330Ω 5 times		
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.7 -2018

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

12. Precautions and Warranty

12.1. Safety

12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.

12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2. Handling

12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.

12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3. Storage

12.3.1. Do not store the LCD module beyond the specified temperature ranges.

12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

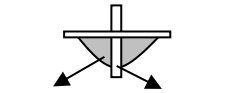
Maximum Solder Temperature: 370℃

Maximum Solder Time: 3s at the maximum temperature

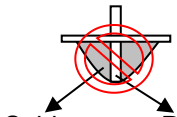
Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



Recommended



Not Recommended

12.4.2. Pins of EL

12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270～290℃

Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

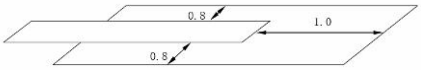
12.4.2.6. Solder Wetting

Recommended Not Recommended

12.4.2.7. The type of the solder iron:

Recommended Not Recommended

12.4.2.8. Solder Pad



12.5. Operation

12.5.1. Do not drive LCD with DC voltage

12.5.2. Response time will increase below lower temperature

12.5.3. Display may change color with different temperature

12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.

12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.

12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.

12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.

12.5.8. Do not display the fixed pattern for long time（we suggest the time not longer than one hour）because it will develop image sticking due to the TFT structure.

12.6. Static Electricity

12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.

12.6.2. The normal static prevention measures should be observed for work clothes and benches.

12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7. Limited Warranty

12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.

12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.

12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Packaging

TBD

14. Outline Drawing